

SUGGESTED CLASS AND SUBCLASS ISSUE CLASSIFICATION		AVAILABLE COPY				PATENT NUMBER	
U.S. UTILITY Patent Application							
		O.I.P.E.		PATENT DATE			
		SCANNED <b>102</b> OA <b>100</b>					
APPLICATION NO. <b>09/945241</b>		CONT/PRIOR <b>F</b>	CLASS <b>257</b> <b>438</b>	SUBCLASS <b>612</b>	ART UNIT <b>2812</b>	EXAMINER <b>Nguyen, H.G.</b>	
APPLICANTS	Fumiaki Matsushima Tsutomu Ota Akira Makabe						
TITLE	Method for forming a bump, semiconductor device and method of fabricating same, semiconductor chip, circuit board, and electronic instrument						
PTO-2040 12/99							
ISSUING CLASSIFICATION							
ORIGINAL		CROSS REFERENCE(S)					
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION							
Continued on Issue Slip Inside File Jacket							
TERMINAL DISCLAIMER		DRAWINGS			CLAIMS ALLOWED		
<input type="checkbox"/> The term of this patent, subsequent to _____ (date) has been disclaimed.		Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____.					NOTICE OF ALLOWANCE MAILED		
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.					ISSUE FEE		
		(Assistant Examiner)	(Date)	(Primary Examiner)	(Date)	Amount Due	Date Paid
ISSUE BATCH NUMBER							
(Legal Instruments Examiner) (Date)							

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